

NBSG11

2.5V/3.3V SiGe 1:2 Differential Clock Driver with RSECL* Outputs

*Reduced Swing ECL

The NBSG11 is a 1-to-2 differential fanout buffer, optimized for low skew and ultra-low JITTER.

Inputs incorporate internal 50 Ω termination resistors and accept NECL (Negative ECL), PECL (Positive ECL), CML, LVCMOS, LVTTTL, or LVDS. Outputs are RSECL (Reduced Swing ECL), 400 mV.

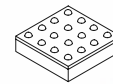
- Maximum Input Clock Frequency up to 12 GHz Typical
- Maximum Input Data Rate up to 12 Gb/s Typical
- 30 ps Typical Rise and Fall Times
- 125 ps Typical Propagation Delay
- RSPECL Output with Operating Range: $V_{CC} = 2.375\text{ V}$ to 3.465 V with $V_{EE} = 0\text{ V}$
- RSNECL Output with RSNECL or NECL Inputs with Operating Range: $V_{CC} = 0\text{ V}$ with $V_{EE} = -2.375\text{ V}$ to -3.465 V
- RSECL Output Level (400 mV Peak-to-Peak Output), Differential Output Only
- 50 Ω Internal Input Termination Resistors
- Compatible with Existing 2.5 V/3.3 V LVEP, EP, and LVEL Devices



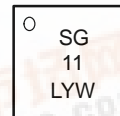
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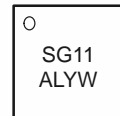
MARKING DIAGRAM*



FCBGA-16
BA SUFFIX
CASE 489



QFN-16
MN SUFFIX
CASE 485G



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week

*For further details, refer to Application Note AND8002/D

ORDERING INFORMATION

Device	Package	Shipping
NBSG11BA	4x4 mm FCBGA-16	100 Units / Tray
NBSG11BAR2	4x4 mm FCBGA-16	500 / Tape & Reel
NBSG11MN	3x3 mm QFN-16	123 Units / Rail
NBSG11MNR2	3x3 mm QFN-16	3000 / Tape & Reel

Board	Description
NBSG11BAEVB	NBSG11BA Evaluation Board



NBSG11

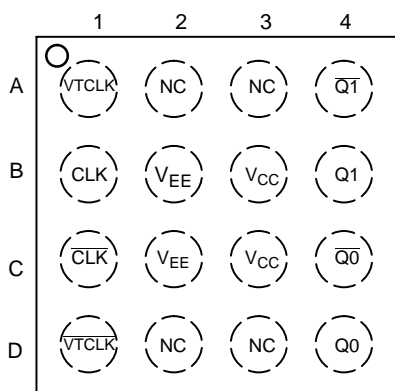


Figure 1. BGA-16 Pinout (Top View)

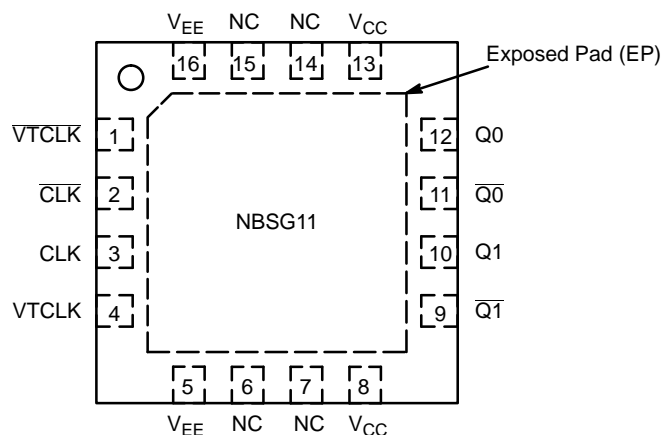


Figure 2. QFN-16 Pinout (Top View)

Table 1. Pin Description

Pin		Name	I/O	Description
BGA	QFN			
D1	1	\overline{VTCLK}	-	Internal 50 Ω Termination Pin. See Table 2.
C1	2	\overline{CLK}	ECL, CML, LVCMOS, LVDS, LVTTTL Input	Inverted Differential Input. Internal 75 k Ω to V_{EE} and 36.5 k Ω to V_{CC} .
B1	3	CLK	ECL, CML, LVCMOS, LVDS, LVTTTL Input	Noninverted Differential Input. Internal 75 k Ω to V_{EE} .
A1	4	VTCLK	-	Internal 50 Ω Termination Pin. See Table 2.
B2,C2	5,16	V_{EE}	-	Negative Supply Voltage
A2,A3,D2,D3	6,7,14,15	NC	-	No Connect
B3,C3	8,13	V_{CC}	-	Positive Supply Voltage
A4	9	$\overline{Q1}$	RSECL Output	Inverted Differential Output 1. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2 V$
B4	10	Q1	RSECL Output	Noninverted Differential Output 1. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2 V$
C4	11	$\overline{Q0}$	RSECL Output	Inverted Differential output 0. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2 V$
D4	12	Q0	RSECL Output	Noninverted Differential Output 0. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2 V$
N/A	-	EP	-	Exposed Pad (Note 2)

1. The NC pins are electrically connected to the die and must be left open.
2. All V_{CC} and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation. The thermally exposed pad on package bottom (see case drawing) must be attached to a heat-sinking conduit.
3. In the differential configuration when the input termination pins (\overline{VTCLK} , $VTCLK$) are connected to a common termination voltage, and if no signal is applied then the device will be susceptible to self-oscillation.

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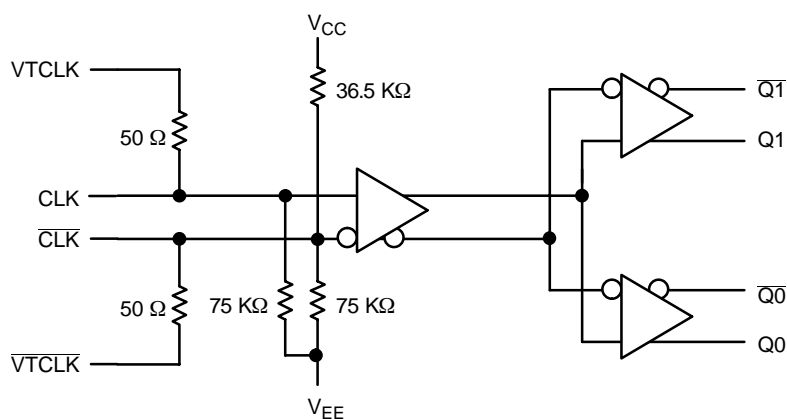


Figure 3. Logic Diagram

Table 2. Interfacing Options

INTERFACING OPTIONS	CONNECTIONS
CML	Connect VTCLK and VTCLK to V _{CC}
LVDS	Connect VTCLK and VTCLK together
AC-COUPLED	Bias VTCLK and VTCLK Inputs within (VIHCMR) Common Mode Range
RSECL, PECL, NECL	Standard ECL Termination Techniques
LVTTTL, LVCMOS	An external voltage should be applied to the unused complementary differential input. Nominal voltage is 1.5 V for LVTTTL and V _{CC} /2 for LVCMOS inputs.

Table 3. ATTRIBUTES

Characteristics	Value
Internal Input Pulldown Resistor (CLK, CLK)	75 kΩ
Internal Input Pullup Resistor (CLK)	36.5 kΩ
ESD Protection	Human Body Model Machine Model
	> 2 kV > 100 V
Moisture Sensitivity (Note 4)	FCBGA-16 QFN-16
	Level 3 Level 1
Flammability Rating	Oxygen Index: 28 to 34
	UL 94 V-0 @ 0.125 in
Transistor Count	125
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

4. For additional information, see Application Note AND8003/D.

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Table 4. MAXIMUM RATINGS (Note 5)

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V _{CC}	Positive Power Supply	V _{EE} = 0 V		3.6	V
V _{EE}	Negative Power Supply	V _{CC} = 0 V		-3.6	V
V _I	Positive Input Negative Input	V _{EE} = 0 V V _{CC} = 0 V	V _I ≤ V _{CC} V _I ≥ V _{EE}	3.6 -3.6	V V
V _{INPP}	Differential Input Voltage D - \bar{D}	V _{CC} - V _{EE} ≥ 2.8 V V _{CC} - V _{EE} < 2.8 V		2.8 V _{CC} - V _{EE}	V V
I _{out}	Output Current	Continuous Surge		25 50	mA mA
T _A	Operating Temperature Range	16 FCBGA 16 QFN		-40 to +70 -40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ _{JA}	Thermal Resistance (Junction-to-Ambient) (Note 6)	0 LFPM 500 LFPM 0 LFPM 500 LFPM	16 FCBGA 16 FCBGA 16 QFN 16 QFN	108 86 41.6 35.2	°C/W °C/W °C/W °C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	1S2P (Note 6) 2S2P (Note 7)	16 FCBGA 16 QFN	5.0 4.0	°C/W °C/W
T _{sol}	Wave Solder	< 15 Seconds		225	°C

5. Maximum Ratings are those values beyond which device damage may occur.

6. JEDEC standard multilayer board - 1S2P (1 signal, 2 power).

7. JEDEC standard multilayer board - 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 5. DC CHARACTERISTICS, INPUT WITH RSPECL OUTPUT V_{CC} = 2.5 V; V_{EE} = 0 V (Note 8)

Symbol	Characteristic	-40°C			25°C			70°C(BGA)/85°C(QFN)**			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I _{EE}	Negative Power Supply Current	45	60	75	45	60	75	45	60	75	mA
V _{OH}	Output HIGH Voltage (Note 9)	1450	1530	1575	1525	1565	1600	1550	1590	1625	mV
V _{OUTPP}	Output Amplitude Voltage	350	410	525	350	410	525	350	410	525	mV
V _{IH}	Input HIGH Voltage (Single-Ended) (Note 11)	V _{CC} - 1435 mV	V _{CC} - 1000 mV*	V _{CC}	V _{CC} - 1435 mV	V _{CC} - 1000 mV*	V _{CC}	V _{CC} - 1435 mV	V _{CC} - 1000 mV*	V _{CC}	V
V _{IL}	Input LOW Voltage (Single-Ended) (Note 12)	V _{IH} - 2.5 V	V _{CC} - 1400 mV*	V _{IH} - 150 mV	V _{IH} - 2.5 V	V _{CC} - 1400 mV*	V _{IH} - 150 mV	V _{IH} - 2.5 V	V _{CC} - 1400 mV*	V _{IH} - 150 mV	V
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 10)	1.2		2.5	1.2		2.5	1.2		2.5	V
R _{TIN}	Internal Input Termination Resistor	45	50	55	45	50	55	45	50	55	Ω
I _{IH}	Input HIGH Current (@ V _{IH} , V _{IHMAX})		80	150		80	150		80	150	μA
I _{IL}	Input LOW Current (@ V _{IL} , V _{ILMIN})		25	100		25	100		25	100	μA

NOTE: SiGe circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 lpm is maintained.

8. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.125 V to -0.965 V.

9. All loading with 50 Ω to V_{CC} - 2.0 V. V_{OH}/V_{OL} measured at V_{IH}/V_{IL}.

10. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

11. V_{IH} cannot exceed V_{CC}.

12. V_{IL} always ≥ V_{EE}.

*Typicals used for testing purposes.

**The device packaged in FCBGA-16 have maximum temperature specification of 70°C and devices packaged in QFN-16 have maximum temperature specification of 85°C.

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Table 6. DC CHARACTERISTICS, INPUT WITH RSPECL OUTPUT $V_{CC} = 3.3\text{ V}$; $V_{EE} = 0\text{ V}$ (Note 13)

Symbol	Characteristic	-40 °C			25 °C			70 °C(BGA)/85 °C(QFN)**			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Negative Power Supply Current	45	60	75	45	60	75	45	60	75	mA
V_{OH}	Output HIGH Voltage (Note 14)	2250	2330	2375	2325	2365	2400	2350	2390	2425	mV
V_{OUTPP}	Output Amplitude Voltage	350	410	525	350	410	525	350	410	525	mV
V_{IH}	Input HIGH Voltage (Single-Ended) (Note 16)	$V_{CC} - 1435\text{ mV}$	$V_{CC} - 1000\text{ mV}^*$	V_{CC}	$V_{CC} - 1435\text{ mV}$	$V_{CC} - 1000\text{ mV}^*$	V_{CC}	$V_{CC} - 1435\text{ mV}$	$V_{CC} - 1000\text{ mV}^*$	V_{CC}	V
V_{IL}	Input LOW Voltage (Single-Ended) (Note 17)	$V_{IH} - 2.5\text{ V}$	$V_{CC} - 1400\text{ mV}^*$	$V_{IH} - 150\text{ mV}$	$V_{IH} - 2.5\text{ V}$	$V_{CC} - 1400\text{ mV}^*$	$V_{IH} - 150\text{ mV}$	$V_{IH} - 2.5\text{ V}$	$V_{CC} - 1400\text{ mV}^*$	$V_{IH} - 150\text{ mV}$	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Note 15) (Differential Configuration)	1.2		3.3	1.2		3.3	1.2		3.3	V
R_{TIN}	Internal Input Termination Resistor	45	50	55	45	50	55	45	50	55	Ω
I_{IH}	Input HIGH Current (@ V_{IH} , V_{IHMAX})		80	150		80	150		80	150	μA
I_{IL}	Input LOW Current (@ V_{IL} , V_{ILMIN})		25	100		25	100		25	100	μA

NOTE: SiGe Circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 l/fpm is maintained.

13. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.925 V to -0.165 V.

14. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$. V_{OH}/V_{OL} measured at V_{IH}/V_{IL} .

15. V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

16. V_{IH} cannot exceed V_{CC} .

17. V_{IL} always $\geq V_{EE}$.

*Typicals used for testing purposes.

**The device packaged in FCBGA-16 have maximum temperature specification of 70°C and devices packaged in QFN-16 have maximum temperature specification of 85°C.

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Table 7. DC CHARACTERISTICS, NECL OR RSNECL INPUT WITH NECL OUTPUT

$V_{CC} = 0\text{ V}$; $V_{EE} = -3.465\text{ V}$ to -2.375 V (Note 18)

Symbol	Characteristic	-40 °C			25 °C			70 °C(BGA)/85 °C(QFN)**			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Negative Power Supply Current	45	60	75	45	60	75	45	60	75	mA
V_{OH}	Output HIGH Voltage (Note 19)	-1050	-970	-925	-975	-935	-900	-950	-910	-875	mV
V_{OUTPP}	Output Amplitude Voltage	350	410	525	350	410	525	350	410	525	mV
V_{IH}	Input HIGH Voltage (Single-Ended) (Note 21)	$V_{CC}-1435\text{ mV}$	$V_{CC}-1000\text{ mV}^*$	V_{CC}	$V_{CC}-1435\text{ mV}$	$V_{CC}-1000\text{ mV}^*$	V_{CC}	$V_{CC}-1435\text{ mV}$	$V_{CC}-1000\text{ mV}^*$	V_{CC}	V
V_{IL}	Input LOW Voltage (Single-Ended) (Note 22)	$V_{IH}-2.5\text{ V}$	$V_{CC}-1400\text{ mV}^*$	$V_{IH}-150\text{ mV}$	$V_{IH}-2.5\text{ V}$	$V_{CC}-1400\text{ mV}^*$	$V_{IH}-150\text{ mV}$	$V_{IH}-2.5\text{ V}$	$V_{CC}-1400\text{ mV}^*$	$V_{IH}-150\text{ mV}$	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 20)	$V_{EE}+1.2$		0.0	$V_{EE}+1.2$		0.0	$V_{EE}+1.2$		0.0	V
R_{TIN}	Internal Input Termination Resistor	45	50	55	45	50	55	45	50	55	Ω
I_{IH}	Input HIGH Current (@ V_{IH} , V_{IHMAX})		80	150		80	150		80	150	μA
I_{IL}	Input LOW Current (@ V_{IL} , V_{ILMIN})		25	100		25	100		25	100	μA

NOTE: SiGe circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

18. Input and output parameters vary 1:1 with V_{CC} .

19. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$. V_{OH}/V_{OL} measured at V_{IH}/V_{IL} .

20. V_{IHCMR} min varies 1:1 with V_{EE} . V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

21. V_{IH} cannot exceed V_{CC} .

22. V_{IL} always $\geq V_{EE}$.

*Typicals used for testing purposes.

**The device packaged in FCBGA-16 have maximum temperature specification of 70°C and devices packaged in QFN-16 have maximum temperature specification of 85°C.

Table 8. AC CHARACTERISTICS for FCBGA-16

$V_{CC} = 0\text{ V}$; $V_{EE} = -3.465\text{ V}$ to -2.375 V or $V_{CC} = 2.375\text{ V}$ to 3.465 V ; $V_{EE} = 0\text{ V}$

Symbol	Characteristic	-40 °C			25 °C			70 °C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Frequency (See Figure 4. $F_{max}/JITTER$) (Note 23)	10.709	12		10.709	12		10.709	12		GHz
t_{PLH} , t_{PHL}	Propagation Delay to Output Differential	90	125	160	90	125	160	90	125	160	ps
t_{SKEW}	Duty Cycle Skew (Note 24) Within-Device Skew (Note 25) Device-to-Device Skew (Note 26)		3 6 25	15 15 50		3 6 25	15 15 50		3 6 25	15 15 50	ps
t_{JITTER}	RMS Random Clock Jitter $f_{in} < 10\text{ GHz}$ Peak-to-Peak Data Dependent Jitter $f_{in} < 10\text{ Gb/s}$		0.2 TBD	1		0.2 TBD	1		0.2 TBD	1	ps
V_{INPP}	Input Voltage Swing/Sensitivity (Differential Configuration) (Note 27)	75		2600	75		2600	75		2600	mV
t_r , t_f	Output Rise/Fall Times (20% - 80%) @ 1 GHz Q, \bar{Q}	20	30	55	20	30	55	20	30	55	ps

23. Measured using a 500 mV source, 50% duty cycle clock source. All loading with $50\ \Omega$ to $V_{CC}-2.0\text{ V}$. For minimum f_{max} value of 10.709 GHz, output amplitude is approximately 200 mV (as shown in Figure 4, where output P-P spec is shown as a minimum/guarantee of around 150 mV). Input edge rates 40 ps (20% - 80%).

24. See Figure 5. $t_{SKEW} = |t_{PLH} - t_{PHL}|$ for a nominal 50% Differential Clock Input Waveform.

25. Within-Device skew is defined as identical transitions on similar paths through a device.

26. Device-to-device skew for identical transitions at identical V_{CC} levels.

27. V_{INPP} (MAX) cannot exceed $V_{CC} - V_{EE}$.

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Table 9. AC CHARACTERISTICS for QFN-16 $V_{CC} = 0\text{ V}; V_{EE} = -3.465\text{ V to } -2.375\text{ V}$ or $V_{CC} = 2.375\text{ V to } 3.465\text{ V}; V_{EE} = 0\text{ V}$

Symbol	Characteristic	-40 °C			25 °C			85 °C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Frequency (See Figure 4. $F_{max}/JITTER$) (Note 28)	10.5	12		10.5	12		10.5	12		GHz
t_{PLH}, t_{PHL}	Propagation Delay to Output Differential	90	125	160	90	125	160	90	125	160	ps
t_{SKEW}	Duty Cycle Skew (Note 29) Within-Device Skew (Note 30) Device-to-Device Skew (Note 31)		3 6 25	15 15 50		3 6 25	15 15 50		3 6 25	15 15 50	ps
t_{JITTER}	RMS Random Clock Jitter $f_{in} < 10\text{ GHz}$ Peak-to-Peak Data Dependent Jitter $f_{in} < 10\text{ Gb/s}$		0.2 TBD	1		0.2 TBD	1		0.2 TBD	1	ps
V_{INPP}	Input Voltage Swing/Sensitivity (Differential Configuration) (Note 32)	75		2600	75		2600	75		2600	mV
t_r, t_f	Output Rise/Fall Times (20% - 80%) @ 1 GHz Q, \bar{Q}	15	30	55	20	30	55	20	30	55	ps

28. Measured using a 500 mV source, 50% duty cycle clock source. All loading with 50 Ω to $V_{CC}-2.0\text{ V}$. For minimum f_{max} value of 10.5 GHz, output amplitude is approximately 200 mV (as shown in Figure 4, where output P-P spec is shown as a minimum/guarantee of around 150 mV). Input edge rates 40 ps (20% - 80%).

29. See Figure 5. $t_{SKEW} = |t_{PLH} - t_{PHL}|$ for a nominal 50% Differential Clock Input Waveform.

30. Within-Device skew is defined as identical transitions on similar paths through a device.

31. Device-to-device skew for identical transitions at identical V_{CC} levels.

32. V_{INPP} (MAX) cannot exceed $V_{CC} - V_{EE}$.

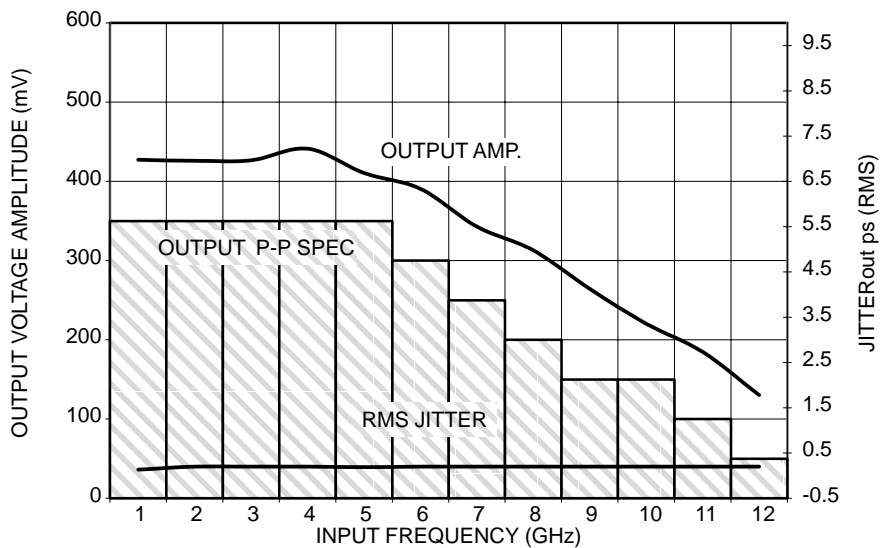


Figure 4. Output Voltage Amplitude (V_{OUTPP}) / RMS Jitter vs. Input Frequency (f_{in}) at Ambient Temperature (Typical)

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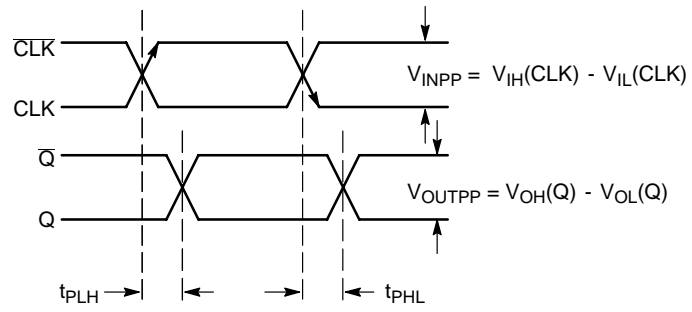


Figure 5. AC Reference Measurement

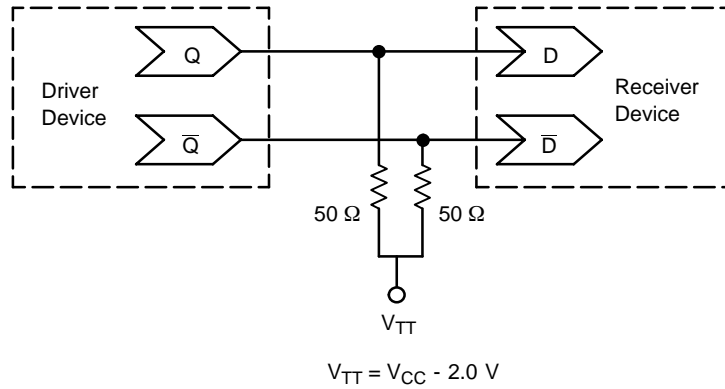


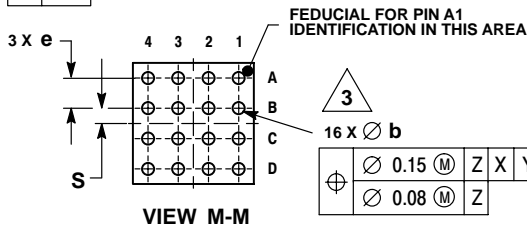
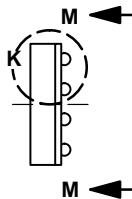
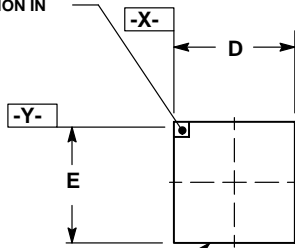
Figure 6. Typical Termination for Output Driver and Device Evaluation
(Refer to Application Note AND8020 - Termination of ECL Logic Devices)

NBSG11

PACKAGE DIMENSIONS

FCBGA-16
BA SUFFIX
 PLASTIC 4X4 (mm) BGA FLIP CHIP PACKAGE
 CASE 489-01
 ISSUE O

LASER MARK FOR PIN 1
 IDENTIFICATION IN
 THIS AREA



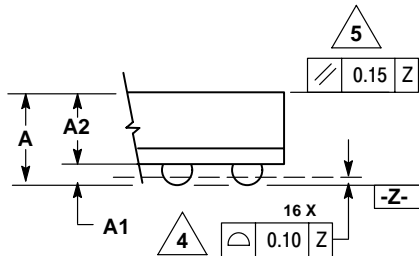
FEDUCIAL FOR PIN A1
 IDENTIFICATION IN THIS AREA

VIEW M-M

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE Z.
4. DATUM Z (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

DIM	MILLIMETERS	
	MIN	MAX
A	1.40	MAX
A1	0.25	0.35
A2	1.20	REF
b	0.30	0.50
D	4.00	BSC
E	4.00	BSC
e	1.00	BSC
S	0.50	BSC

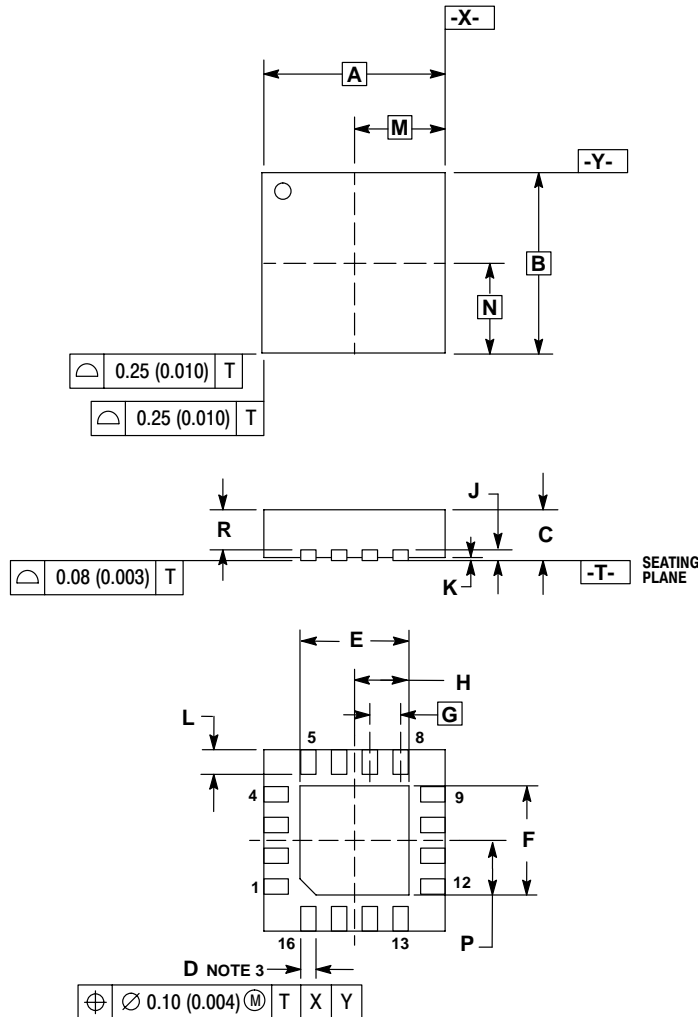


DETAIL K
 ROTATED 90° CLOCKWISE

NBSG11

PACKAGE DIMENSIONS

16 PIN QFN
MN SUFFIX
CASE 485G-01
ISSUE O



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION D APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	3.00 BSC		0.118 BSC	
B	3.00 BSC		0.118 BSC	
C	0.80	1.00	0.031	0.039
D	0.23	0.28	0.009	0.011
E	1.75	1.85	0.069	0.073
F	1.75	1.85	0.069	0.073
G	0.50 BSC		0.020 BSC	
H	0.875	0.925	0.034	0.036
J	0.20 REF		0.008 REF	
K	0.00	0.05	0.000	0.002
L	0.35	0.45	0.014	0.018
M	1.50 BSC		0.059 BSC	
N	1.50 BSC		0.059 BSC	
P	0.875	0.925	0.034	0.036
R	0.60	0.80	0.024	0.031

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